

PATENT ASSIGNMENT

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SUBMISSION TYPE:

NEW ASSIGNMENT

NATURE OF CONVEYANCE:

ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Morihiko Mouri	07/29/2004
Sadayuki Okuma	07/29/2004
Yasushi Takahashi	07/29/2004
Takao Ono	07/29/2004
Yoshihiro Sakaguchi	06/11/2004
Atsushi Nakamura	06/11/2004
Toshio Miyazawa	06/11/2004

RECEIVING PARTY DATA

Name:	Elpida Memory, Inc.
Street Address:	2-1, Yaesu 2-chome, Chuo-ku
City:	Tokyo
State/Country:	JAPAN

Name:	Renesas Eastern Japan Semiconductor, Inc.
Street Address:	3-2, Fujihachi 3-chome, Oume-shi
City:	Tokyo
State/Country:	JAPAN

Name:	Hitachi, Ltd.
Street Address:	6, Kanda Surugadai 4-chome, Chiyoda-ku
City:	Tokyo
State/Country:	JAPAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	10409929

CORRESPONDENCE DATA

PATENT

500007072

REEL: 015132 FRAME: 0267

CH \$40.00 10409929

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Total Attachments: 2

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WN2-2571
2002-107952

UNITED STATES

ASSIGNMENT

Docket No. NECG 20.350

WHEREAS, the below named inventor, ASSIGNOR, has made a certain new and useful invention in :
PACKAGE FOR MOUNTING SEMICONDUCTOR DEVICE

for which

(check one) [] an application is being filed concurrently herewith.

[x] an application for a Patent of the United States was filed on April 10, 2003

[x] and given Application Serial No. 10/409,929

and WHEREAS, Elpida Memory, Inc., Renesas Eastern Japan Semiconductor, Inc., Hitachi, Ltd.

having a place of business at 2-1, Yaesu 2-chome, Chuo-ku, Tokyo, Japan; 3-2, Fujihashi 3-chome, Jume-shi, Tokyo, Japan; 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, ASSIGNEE

is desirous of obtaining the entire right, title and interest in, to and under the said invention and the said application:

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to me in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, the said ASSIGNOR, has sold, assigned, transferred and set over, and by these presents does hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title and interest in, to and under the said invention, and the said United States application and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may hereafter be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights derived from said United States application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventor's certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof;

ASSIGNOR authorizes and requests the Commissioner of Patents and Trademarks of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND ASSIGNOR covenants and agrees that he has full right to convey the entire interest herein assigned, and has not executed, and will not execute, any agreement in conflict herewith.

AND ASSIGNOR further covenants and agrees that he will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries.

Full name of sole or first inventor MORIHIKO MOURI

Inventor's signature Morihiko Mouri

Residence Tokyo, Japan

Post Office Address c/o Elpida Memory, Inc., 2-1, Yaesu 2-chome, Chuo-ku, Tokyo, Japan



Date July 29, 2004

Citizenship Japanese

Full name of second joint inventor, if any SADAYUKI OKUMA

Second Inventor's signature Sadayuki Okuma

Residence Tokyo, Japan

Post Office Address c/o Elpida Memory, Inc., 2-1, Yaesu 2-chome, Chuo-ku, Tokyo, Japan



Date July 29, 2004

Citizenship Japanese

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Full name of fourth joint inventor, if any TAKAO ONO
Fourth Inventor's signature Takao Ono Date July 29, 2004
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Full name of sixth joint inventor, if any ATSUSHI NAKAMURA
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Full name of seventh joint inventor, if any TOSHIO MIYAZAWA
Seventh Inventor's signature Toshio Miyazawa Date June 11, 2004
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Full name of eighth joint inventor, if any _____
Eighth Inventor's signature _____ Date _____
Residence _____ Citizenship _____
Post Office Address _____

Full name of ninth joint inventor, if any _____
Ninth Inventor's signature _____ Date _____
Residence _____ Citizenship _____
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RECORDED: 09/15/2004

REEL: 015132 FRAME: 0270